

WLCSP16 1.96x1.76x0.586 CASE 567SE ISSUE O DATE 30 NOV 2016 0.03 C \frown /F\ E A 2X В 0.40 (Ø0.20) A1 Cu Pad 📵 📵 🎯 🎯 BALL A1 0000 D **INDEX AREA** \varTheta 🔘 🕲 📵 0.40 (Ø0.30) Solder 000 Mask Opening 0.03 C \square RECOMMENDED LAND PATTERN TOP VIEW 2X (NSMD PAD TYPE) //|0.06|C 0.378±0.018 0.625 /e\ 0.05 C 0.547 0.208±0.021 0000 $\Omega \Omega I$ С SEATING /D\ PLANE SIDE VIEWS ⊕ 0.005@ C A B NOTES: Ø0.260±0.02 0.40 16X A. NO JEDEC REGISTRATION APPLIES. $\oplus \oplus \odot \oplus$ D **B. DIMENSIONS ARE IN MILLIMETERS.** 0000 С C. DIMENSIONS AND TOLERANCE ⊕ O|O O В ⊢(Y) ±0.018 PER ASME Y14.5M, 1994. 0.40 $00 \oplus$ Đ D. DATUM C IS DEFINED BY THE SPHERICAL ∕₣∖ 2 3 1 CROWNS OF THE BALLS. (X) ±0.018 E PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS). BOTTOM VIEW /F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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